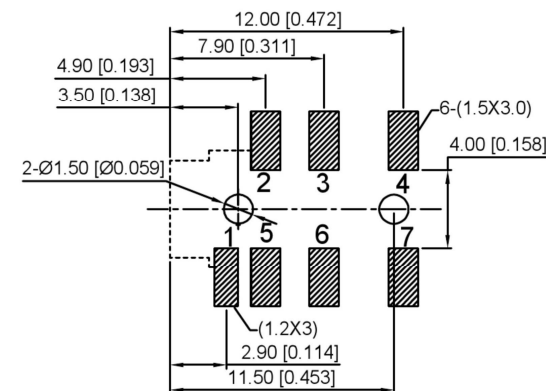
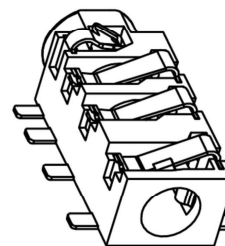
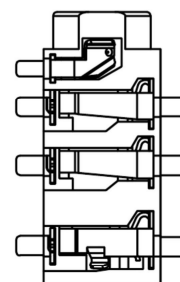
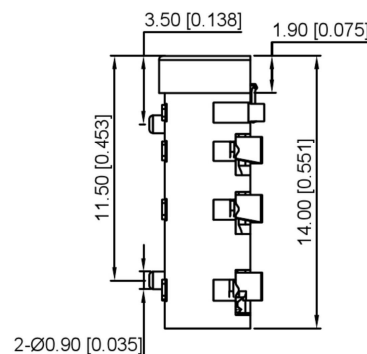




PCB LAYOUT TOP VIEW



SPECIFICATIONS:

1.ELECTRICAL CHARACTERISTICS:

1-1. RATING:

1-2. CONTACT RESISTANCE: 30mΩ MAX.(INITIAL)

1-3. DIELECTRIC WITHSTANDING VOLTAGE: 500V
AC FOR ONE MINUTE.

1-4. INSULATION RESISTANCE: 100MΩ MIN.
MEASURED BY 500V DC.

2. MECHANICAL CHARACTERISTICS:

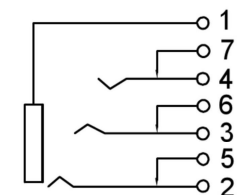
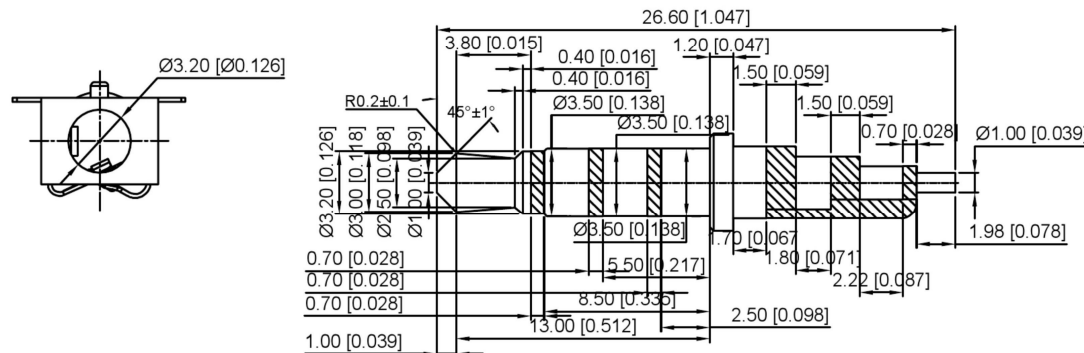
2-1. INSERTION FORCE: 0.3~3.0 KGF.

2-2. WITHDRAWAL FORCE: 0.3~3.0 KGF.

3.LIFE TEST: 5.000 CYCLES MIN.

4. FOR REFLOW SOLDERING LEAD-FREE PROCESS.

5. *REPRESENT CRITICAL DIMENSIONS.



CIRCUIT DIAGRAM

	MATERIAL	PLATING
terminal 1	Phosphor Bronze	Gold
terminal 2	Phosphor Bronze	Gold
terminal 3	Phosphor Bronze	Gold
terminal 4	Phosphor Bronze	Gold
terminal 5	Phosphor Bronze	Gold
terminal 6	Phosphor Bronze	Gold
terminal 7	Phosphor Bronze	Gold
plastic	High Temp. Thermoplastic	

DSND		SCALE: N/A	MODEL TYPE: 3.5 PHONE JACK		
DWN		VIEW: 	PART NO.: PJ-3507-SMT		
CHKD		UNIT: mm/in	DWG NO.:		
APPD		SIZE: A4			
ANG ELECTRONIC CO., LTD			WEIGHT	SHEET	REVISION
				1/1	A0



DONG GUAN XI BANG ELECTRONIC CO., LTD

				ANGLAR	±5°
				L ≤ 4	±0.2
				4 < L ≤ 16	±0.3
				16 < L ≤ 63	±0.4
	DATE	REVISED	APPROVED	L > 63	±0.5
REVISIONS				UNSPECIFIED TOLERANCES	
www.alpsr.com www.gdxjdz.com www.xbswitch.com					